



CONTACT

SHENMAO America, Inc.
Andy Chueh, Director
E-mail: andy_chueh@shenmao.us

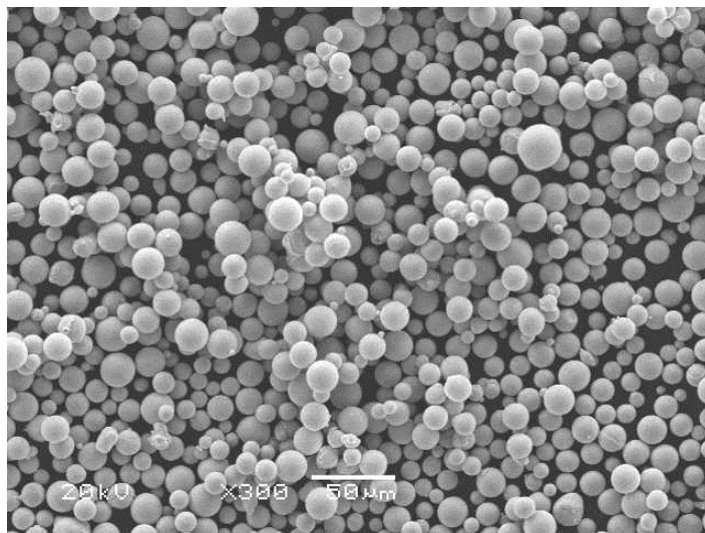
FOR IMMEDIATE RELEASE

SHENMAO Launches No-Clean Ultra-Fine Pitch Solder Paste PF606-P279L for Mini LED Production

SAN JOSE, CA — November 2025 — SHENMAO Technology, Inc. has introduced its new No-Clean Ultra-Fine Pitch Printing Paste PF606-P279L, designed for the precision demands of mini-LED manufacturing.

Built with Type 6 and Type 7 solder powder technology, PF606-P279L offers uniform particle shape and size for smooth, consistent printing—even through stencil apertures as small as 60 microns. The paste delivers stable performance with no splashing, minimal voiding, and strong die stability, helping manufacturers maintain high yields on fine-pitch assemblies.

The formulation can also be adapted for Type 8 and finer powders, making it suitable for future-generation mini and micro-LED designs. PF606-P279L is available in SAC305 and multiple Sn-based alloys, including Sn-Sb, Sn-Bi, and Sn-Bi-Ag, giving users flexibility to meet various process and reliability requirements.



Typical uses include mini-LED backlight panels for TVs and tablets, as well as display modules for outdoor signage and large-format indoor screens.

To learn more about SHENMAO's high-performance solder materials, visit www.SHENMAO.com.

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About SHENMAO

SHENMAO is dedicated to the production of solder products including Water Soluble and No-clean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.